

General Plating

TABLE- 1 (Tin-Plated)

| Plating Code | Top Plating Thickness | Under Plating Thickness | Area | Match Type |
|--------------|-----------------------|-------------------------|---------|--|
| 1 | 80 μ ” Tin Min. | 30 μ ” Nickel Min. | Overall | Crimp clip terminal |
| | 100 μ ” Tin Min. | 30 μ Nickel Min. | Overall | Solder tail terminal & Board in terminal |
| | 120 μ ” Tin Min. | 30 μ Nickel Min. | Overall | Square or round pin |
| | 120 μ ” Tin | 50 μ Nickel Min. | Overall | SMT type terminal |

TABLE- 2 (Gold -Plated)

| Plating Code | Top Plating Thickness | Under Plating Thickness | Area | Match Type |
|--------------|----------------------------------|-------------------------|--------------|---------------------|
| 2 | 0.8 μ ” Gold Min. | 50 μ ” Nickel Min. | Overall | Square or round pin |
| | 1.2 μ ” Gold Min. | | | Other type |
| 3 | 15 μ ” Gold Min. | 50 μ ” Nickel | Overall | All type |
| 4 | 30 μ ” Gold Min. | 50 μ ” Nickel | Overall | All type |
| 5 | 50 μ ” Gold Min. | 50 μ ” Nickel | Overall | All type |
| 7 | 3 μ ” Gold Min. | 50 μ ” Nickel | Overall | All type |
| 8 | 80 μ ” Gold Plated over | 50 μ ” Nickel | Overall | CP35 |
| 9 | 5 μ ” Gold Plated over | 50 μ ” Nickel | Overall | All type |
| A | Selective 1.2 μ ” Gold Flash | 50 μ ” Nickel | Contact Area | All type |
| B | Selective 15 μ ” Gold | 50 μ ” Nickel | Contact Area | All type |
| C | Selective 30 μ ” Gold | 50 μ ” Nickel | Contact Area | All type |
| D | Selective 10 μ ” Gold | 50 μ ” Nickel | Contact Area | All type |



| | | | | |
|---|---------------------------|--|--------------|----------|
| E | Selective 50 μ ” Gold | 50 μ ” Nickel | Contact Area | All type |
| F | Selective 80 μ ” Gold | 50 μ ” Nickel | Contact Area | CP35 |
| G | Selective 5 μ ” Gold | 50 μ ” Nickel | Contact Area | CCF |
| I | Selective 15 μ ” Gold | 1.2 μ ” Gold Flash Plated over 50 μ ” Nickel | Contact Area | All type |
| J | Selective 30 μ ” Gold | 1.2 μ ” Gold Flash Plated over 50 μ ” Nickel | Contact Area | All type |
| K | Selective 5 μ ” Gold | 80 μ ” Nickel | Contact Area | All type |

SOLDERABILITY:

| TEST ITEM | TEST CONDITION | PROCESS | TEST REQUIREMENT |
|---------------|---|-------------------|----------------------------------|
| Solderability | Soldering time: 5 \pm 0.5 Second Soldering pot: 230 \pm 5 $^{\circ}$ C | Sn - Pb Process | Minimum: 95% of immersed area |
| | Soldering time: 3 \pm 0.5 Second Soldering pot: 245 \pm 5 $^{\circ}$ C | Lead Free Process | |